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|---|---|---|--|--|--|--|--|
| 1. | A. | Name of conveying parties: | 2. A. Name and address of receiving party: | | | | |
| | | [1] Hidehiko YAJIMA [2] Hiroshi KIYA | SEIKO EPSON CORPORATION 4-1, NISHI-SHINJUKU 2-CHOME SHINJUKU-KU, TOKYO | | | | |
| | В. | Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No | JAPAN | | | | |
| 3. | A. | Nature of conveyance: | B. Additional name(s) & address(es) attached? ☐ Yes ☒ No | | | | |
| | \boxtimes | Assignment | | | | | |
| | | Security Agreement Change of Name | | | | | |
| | | Other | | | | | |
| | В. | Execution Date: [1] & [2]: October 29, 2007 | | | | | |
| 4. | \boxtimes | This document is being filed together with a new application. | | | | | |
| | A. | Patent Application No.(s) | B. Patent No.(s) | | | | |
| | Additional numbers attached? | | | | | | |
| | C. Title of Application: <u>INTEGRATED CIRCUIT DEVICE AND ELECTRONIC INSTRUMENT</u> | | | | | | |
| 5. | | ne and address of party to whom correspondence cerning document should be mailed: | 6. Total number of applications and patents involved: 1 | | | | |
| | Name: James A. Oliff | | 7. A. Total fee (37 CFR 3.41)\$ 40.00 | | | | |
| | | | B. Enclosed (Check No. 199221) | | | | |
| | Ad | dress: OLIFF & BERRIDGE, PLC P.O. Box 320850 Alexandria, VA 22320-4850 | Credit any overpayment or charge any underpayment to deposit account number 15-0461. | | | | |
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| 9. | To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. 11/19/2007 MGETACHE 00000044 11984076 | | | | | | |
| | Pate: Newember 13, 2007 40.00 accluding cover sheet, attachments, and document: 3 | | | | | | |

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矢島 秀彦,木屋 洋,

は、ある発明を創出し、これについて合衆国特許出願は

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□ PCT国際出願 として に出願され、
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集積回路装置及び電子機器

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Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Hidehiko YAJIMA, Hiroshi KIYA,

| who have created a certain invention for which an application for | | | | | | |
|---|--|--|--|--|--|--|
| United States Letters Patent | | | | | | |
| executed by ME/US on even date herewith, | | | | | | |
| executed by ME/US on , (respectively), | | | | | | |
| filed on and assigned Serial No. | | | | | | |
| filed as International Application No. filed on | | | | | | |
| and entitled: | | | | | | |
| INTEGRATED CIRCUIT DEVICE AND ELECTRONIC | | | | | | |
| INSTRUMENT | | | | | | |

Do hereby sell, assign and transfer to Seiko Epson Corporation, having a place of business 4-1, Nishi-shinjuku 2-chome, Shinjuku-ku, Tokyo, Japan its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties:

Agree that Seiko Epson Corporation hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes. reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

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さらに、下記に署名した私/私達はこの譲渡書は英語の部分の表現によってのみ解釈されることに同意する。

上記を証明するため、私/私達は下記日付で署名する。

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I/WE, the undersigned do further agree that this Assignment is to be construed solely according to the terms of the English language portions thereof.

IN TESTIMONY WHEREOF I/WE have hereunto set MY/OUR signature seal on the date indicated below.

| 唯一または第一発明者名 | | Full name of sole or first inventor | |
|-----------------|-------------|---|--------------|
| 矢島 秀彦 | | Hidehiko YAJIMA | |
| 発明者の署名 | 日付 | Inventor's signature | Date |
| 失島 秀秀 | 2007年10月29日 | Hidehiko Yajima | Oct 29, 2007 |
| 第二共同発明者(いる場合) | | Full name of Second joint inventor, if any | |
| 木屋 洋 | | Hiroshi KIYA | |
| 第二共同発明者の署名 | 日付 | Second Inventor's signature | Date |
| H.k 0d/11/6/ | | Hiroshi kiya | |
| 不套 是 浑 | 2007年10月29日 | | Oct 19, 2007 |
| 第三共同発明者(いる場合) | | Full name of Third joint inventor, if any | |
| 第三共同発明者の署名 | 日付 | Third Inventor's signature | Date |
| 第四共同発明者(いる場合) | | Full name of Fourth joint inventor, if any | |
| 第四共同発明者の署名 | 日付 | Fourth Inventor's signature | Date |
| 第五共同発明者(いる場合) | 2 | Full name of Fifth joint inventor, if any | |
| 第五共同発明者の署名 | 日付 | Fifth Inventor's signature | Date |
| 第六共同発明者(いる場合) | | Full name of Sixth joint inventor, if any | |
| 第六共同発明者の署名 | 日付 | Sixth Inventor's signature | Date |
| 第七共同発明者(いる場合) | | Full name of Seventh joint inventor, if any | · |
| / 第七共同発明者の署名 | 日付 | Seventh Inventor's signature | Date |
| 第八共同発明者(いる場合) | | Full name of Eighth joint inventor, if any | |
| 第八共同発明者の署名 | 日付 | Eighth Inventor's signature | Date |
| | | | ···· |

2 of 2

PATENT REEL: 020149 FRAME: 0732